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100727362

To the Honorable Commissioner of Patents and Trademarks

Attached original documents or copy thereof.

1. Name of conveying party(ies):

CHUNG-HSING TZU
JUNG-YU LEEAdditional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

3. Nature of conveyance:

☒ Assignment☐ Merger☐ Security Agreement☐ Change of Name☐ Other _____

Execution Date: 5/15/98

2. Name and address of receiving party(ies)

Name: SAMPO SEMICONDUCTOR CORPORATION

Address: 9F, No. 217, Sec. 3,

Nanking E. Rd., Taipei,

Taiwan, R.O.C.

City: Taipei Country: Taiwan, ROC

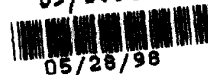
Additional name(s) & address(es) attached? ☐ Yes ☒ No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is: 5/15/98

A. Patent Application No.(s)

B. Patent No.(s)

jc551 U.S. PTO
09/085447

05/28/98

Additional numbers attached? ☐ Yes ☒ No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: MORTON J. ROSENBERG, ESQ.

Internal Address: ROSENBERG, KLEIN &

BILKER

Street Address: 3444 ELLICOTT CENTER DRIVE

06/01/1998 DMCH1 00000029 09085447

SUITE 105

02 FC:561

City: ELLICOTT CITY State: MD ZIP: 21043

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41).....\$ 40.00

☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

MORTON J. ROSENBERG

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document: 2

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

PATENT

REEL: 9205 FRAME: 0594

ASSIGNMENT

(1-5) Insert Name(s) of Inventor(s).

(1) CHUNG-HSING TZU (FAMILY NAME: TZU)
(2) JUNG-YU LEE (FAMILY NAME: LEE)
(3) _____
(4) _____
(5) _____

In consideration of the sum of one dollar (\$1.00) and other good and valuable considerations paid to each of the undersigned, the undersigned agree(s) to assign, and hereby does assign, transfer and set over to

(6) Insert name of Assignee (6) SAMPO SEMICONDUCTOR CORPORATION

(7) Insert address of Assignee (7) 9F, NO. 217, SEC. 3, NANKING E. RD., TAIPEI, TAIWAN, R.O.C.

(hereinafter designated as the Assignee) the entire right, title and interest for the United States, its territories, dependencies and possessions, in the invention, and all applications for patent and any Letters Patent which may be granted therefor, known as

(8) Insert Identification of Invention, such as Title, Case Number or Foreign Application Number (8) Universal Leadframe for Semiconductor Devices and Method for Making the Same

Foreign Application or Case No. _____

for which the undersigned has (have) executed an application for patent in the United States of America

(9) Insert Date of Signing of Application (9) on MAY 15, 1998

(10) Alternative identification for filed applications (10) U.S. application Serial Number _____, filed _____

1) The undersigned agree(s) to execute all papers necessary in connection with the application and any continuing or divisional or reissue applications thereof and also to execute separate assignments in connection with such applications as the Assignee may deem necessary or expedient or essential to its full protection and title in and to the invention hereby transferred.

2) The undersigned agree(s) to execute all papers necessary in connection with any interference which may be declared concerning this application or continuation or division or re-issue thereof and to cooperate with the Assignee in every way possible in obtaining evidence and going forward with such interference.

3) The undersigned agree(s) to perform all affirmative acts which may be necessary to obtain a grant of a valid United States patent to the Assignee.

4) The undersigned agree(s) to communicate to the Assignee or representatives thereof any facts known to me (us) respecting the invention and improvements thereof, and will, upon request, but without expense to me (us), testify in any legal proceedings regarding the invention.

5) The undersigned hereby authorize(s) and request(s) the Commissioner of Patents to issue any and all Letters Patents of the United States resulting from said application or any division or divisions or continuing applications thereof to the said Assignee, as Assignee of the entire interest, and hereby covenants that he has (they have) full right to convey the entire interest herein assigned, and that he has (they have) not executed and will not execute, any agreement in conflict herewith.

6) The undersigned hereby grant(s) the firm of ^{Rosenberg} Klein & Bilker the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

7) This Assignment shall be binding upon my (our) heirs, executors, administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors and/or assigns of the Assignee.

In witness whereof, executed by the undersigned on the date(s) opposite the undersigned name(s).

(1) Date 5/15/98 Name of Inventor Chung-Hsing Tzu CHUNG-HSING TZU
(2) Date 5/15/98 Name of Inventor Jung-Yu Lee JUNG-YU LEE
(3) Date _____ Name of Inventor _____
(4) Date _____ Name of Inventor _____
(5) Date _____ Name of Inventor _____
Date _____ Witness _____
Date _____ Witness _____